

Features

- Advanced Trench Process Technology
- High Input Impedance
- High-Speed Switching
- CMOS Logic Compatible Input
- Marking Code: 7002

Maximum Ratings

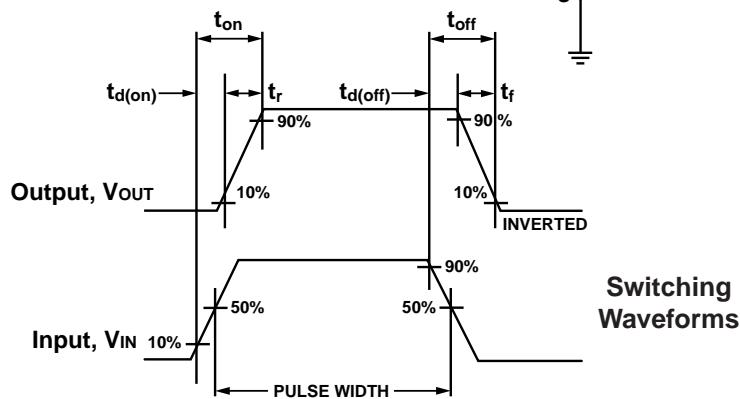
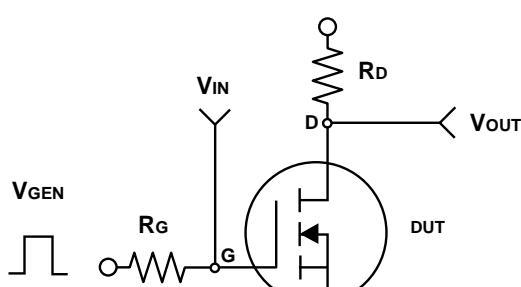
- Operating Temperature: -55°C to +150°C
- Storage Temperature: -55°C to +150°C
- Maximum Thermal Resistance: 417°C/W Junction To Ambient

Parameter	Symbol	Value	Condition
Drain-Source-Voltage	V_{DS}	60V	
Gate-Source-Voltage	V_{GS}	$\pm 20V$	
Continuous Drain Current $T_J = 150^{\circ}C$	I_D	230mA 180mA	$T_A=25^{\circ}C$ $T_A=70^{\circ}C$
Pulsed Drain Current	I_{DM}	1300mA	
Maximum Power Dissipation	P_D	300mW 192mW	$T_A=25^{\circ}C$ $T_A=70^{\circ}C$

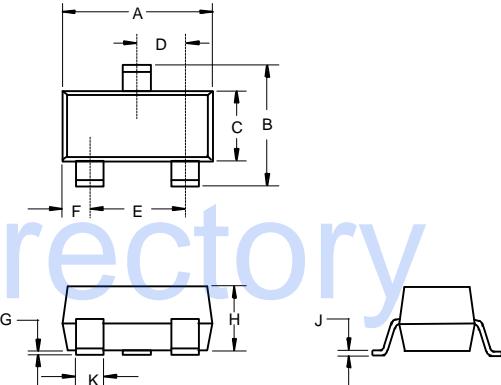
Note: Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

V_{DD}

Switching Test Circuit



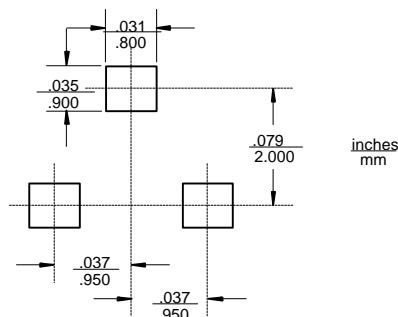
SOT-23



DIMENSIONS

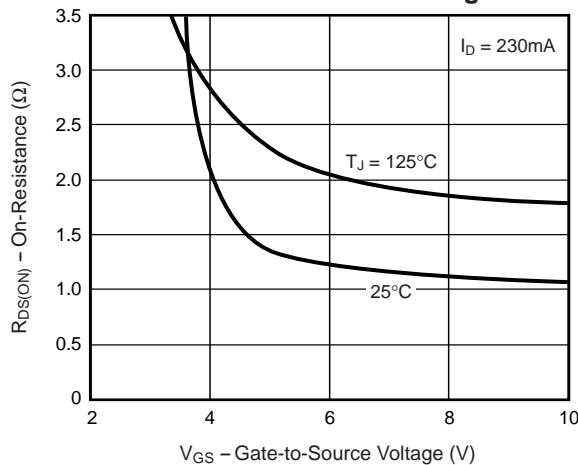
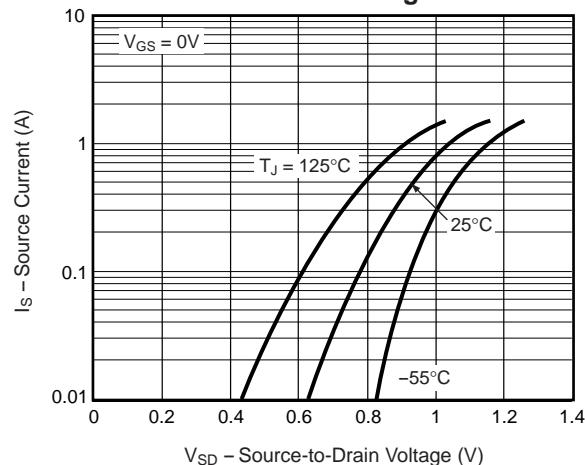
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	.110	.120	2.80	3.04	
B	.083	.098	2.10	2.64	
C	.047	.055	1.20	1.40	
D	.035	.041	.89	1.03	
E	.070	.081	1.78	2.05	
F	.018	.024	.45	.60	
G	.0005	.0039	.013	.100	
H	.035	.044	.89	1.12	
J	.003	.007	.085	.180	
K	.015	.020	.37	.51	

Suggested Solder Pad Layout



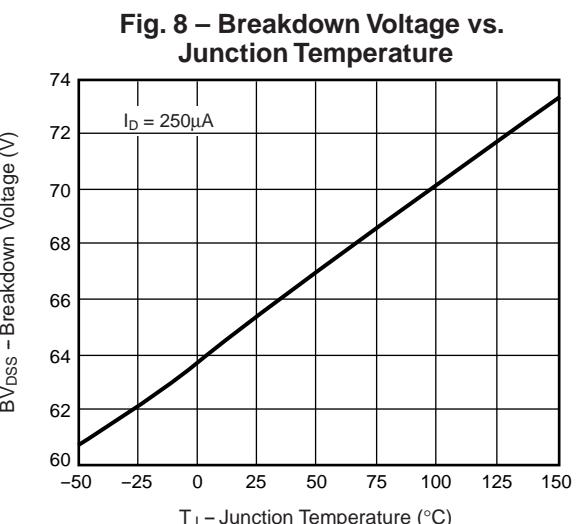
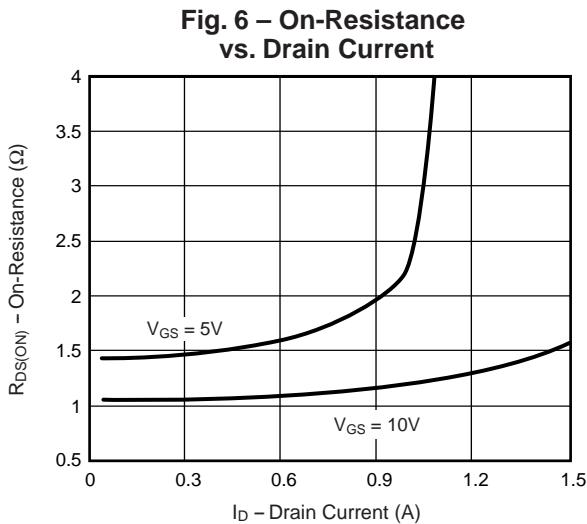
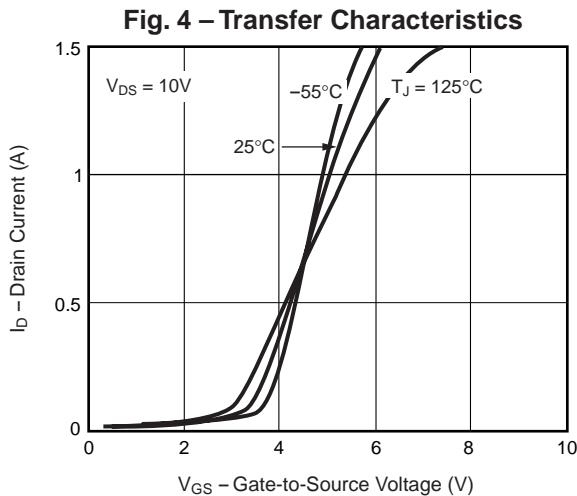
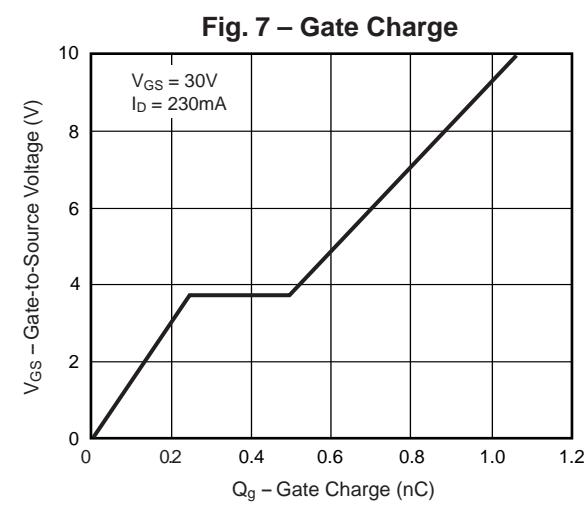
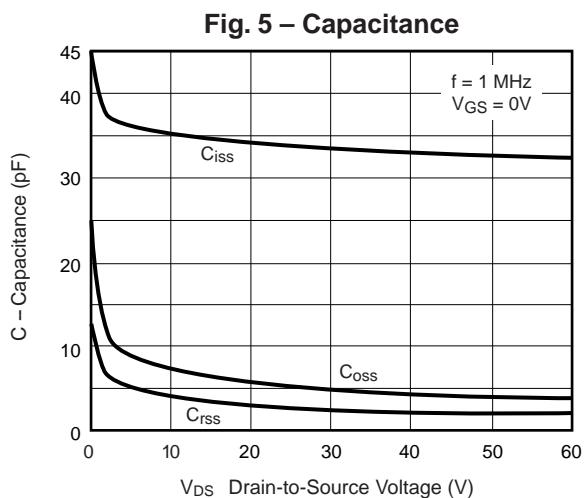
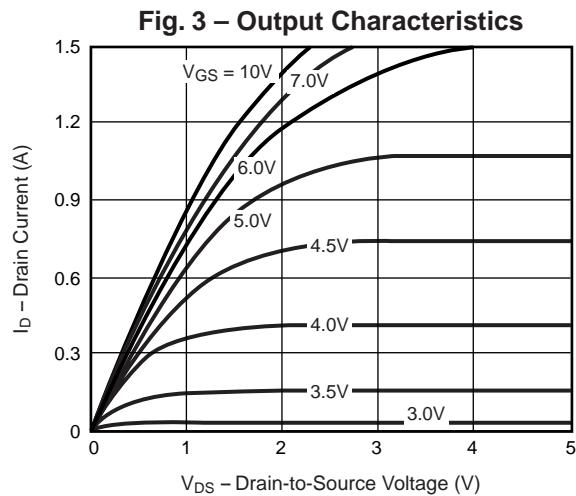
Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 10\mu\text{A}$	60	70	—	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250\mu\text{A}$	1.0	2.0	2.5	V
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	—	—	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}$	—	—	1	μA
		$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$	—	—	500	
On-State Drain Current ⁽¹⁾	$I_{\text{D}(\text{on})}$	$V_{\text{DS}} \geq 7.5\text{V}, V_{\text{GS}} = 10\text{V}$	800	1500	—	mA
Drain-Source On-State Resistance ⁽¹⁾	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 500\text{mA}$	—	1.7	3.0	Ω
		$V_{\text{GS}} = 5\text{V}, I_{\text{D}} = 50\text{mA}$	—	2.5	4.0	
Forward Transconductance ⁽¹⁾	g_{fs}	$V_{\text{DS}} = 10\text{V}, I_{\text{D}} = 200\text{mA}$	—	250	—	mS
Dynamic						
Turn-On Time	t_{on}	$V_{\text{DD}} = 30\text{V}, R_{\text{L}} = 150\Omega$ $I_{\text{D}} = 200\text{mA}, V_{\text{GEN}} = 10\text{V}$ $R_{\text{G}} = 25\Omega$	—	7	20	ns
Turn-Off Time	t_{off}		—	12	20	
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}$ $V_{\text{DS}} = 25\text{V}$ $f = 1.0\text{MHz}$	—	33	50	pF
Output Capacitance	C_{oss}		—	4.3	25	
Reverse Transfer Capacitance	C_{rss}		—	1.6	5	
Source-Drain Diode						
Diode Forward Voltage ⁽¹⁾	V_{SD}	$I_{\text{s}} = 230\text{mA}, V_{\text{GS}} = 0\text{V}$	—	0.85	1.5	V

Notes:(1) Pulse test; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$ **Fig. 1 – On-Resistance vs. Gate-to-Source Voltage****Fig. 2 – Source-Drain Diode Forward Voltage**

2N7002

•M•C•C•



2N7002

•M•C•C•

Fig. 9 – Threshold Voltage

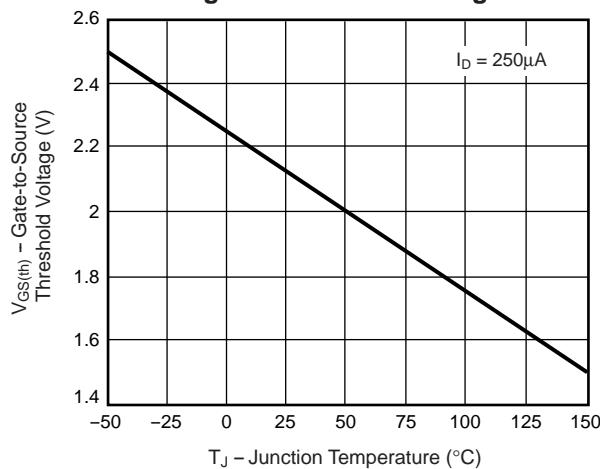


Fig. 10 – On-Resistance vs. Junction Temperature

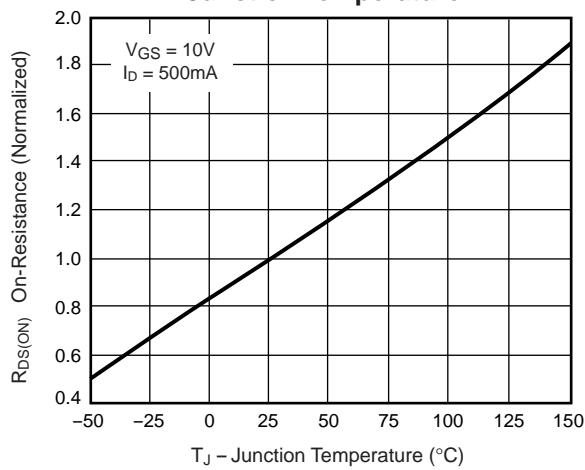


Fig. 11 – Thermal Impedance

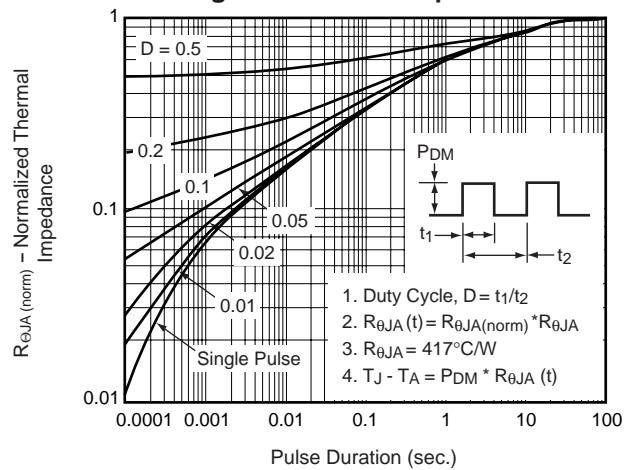


Fig. 12 – Power vs. Pulse Duration

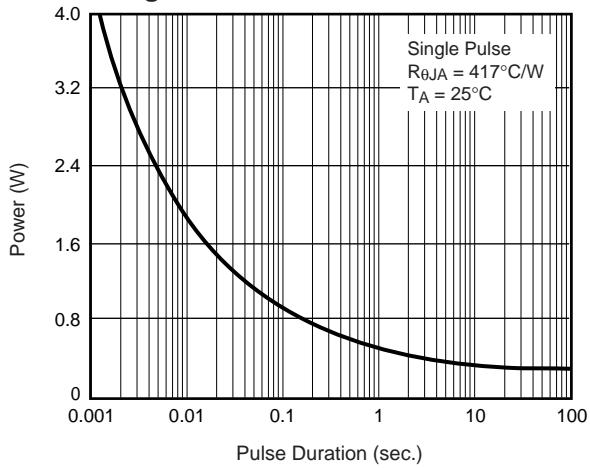


Fig. 13 – Maximum Safe Operating Area

